

ABSTRACT

A hollow sealing structure (1) has a substrate (10), an electronic component (20) that is disposed on Au bumps (25), which are projecting parts provided on the substrate (10), the electronic component (20) being separated from the substrate (10), and a sealing part (30) formed from an insulating material, the sealing part (30) sealing the electronic component in a state in which a hollow region (H) is formed between the electronic component (20) and the substrate (10), and in the entire periphery of the outer periphery of the electronic component in plan view, the sealing part enters from the outer periphery between the electronic component (20) and the substrate (10).